

General Description

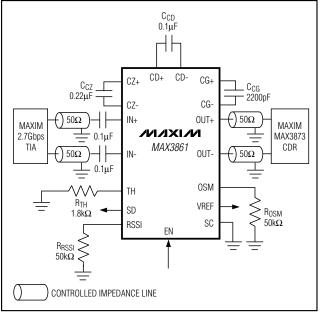
The MAX3861 is a low-power amplifier with automatic gain control (AGC), designed for WDM transmission systems employing optical amplifiers and requiring a vertical threshold adjustment after the post amp. Operating from a single 3.3V supply, this AGC amplifier linearly amplifies/attenuates the input signal while maintaining a fixed output-voltage swing at data rates up to 2.7Gbps. Both the input and output are on-chip terminated to match 50Ω interfaces.

This amplifier has a small-signal bandwidth of 3.4GHz and an input-referred noise of 0.26mV_{RMS}. Over an input signal range of 6mVP-P to 1200mVP-P (46dB), the MAX3861 delivers a constant output amplitude that is adjustable from 400mVP-P to 920mVP-P. Variation in output swing is controlled within 0.2dB over a 16dB input range. The MAX3861 provides a received-signalstrength indicator (RSSI) that is linear, within 2.5%, for input signal levels up to 100mV_{P-P} and an input signal detect (SD) with programmable threshold.

Applications

OC-48/STM-16 Transmission Systems WDM Optical Receivers Long Reach Optical Receivers **Continuous Rate Receivers**

Typical Application Circuit



MIXIM

- Single 3.3V Power Supply
- 72mA Supply Current
- 3.4GHz Small-Signal Bandwidth
- 0.26mV_{RMS} Input-Referred Noise
- ♦ 6mVP-P to 1200mVP-P Input Range (46dB)
- Input Signal Detect with Programmable Threshold

- RSSI (Linear Up to 100mVP-P)
- Adjustable Output Amplitude
- 0.2dB Output Voltage Variation (Over 16dB Input) Signal Variation)

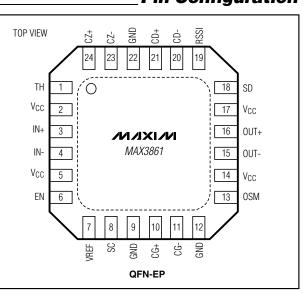
Ordering Information

PART	TEMP RANGE	PIN-PACKAGE
MAX3861EGG	-40°C to +85°C	24 QFN*
MAX3861E/D	-40°C to +85°C	Dice**

*EP = Exposed Pad

**Dice are designed to operate over a -40°C to +120°C junction temperature (TJ) range, but are tested and guaranteed at $T_A = +25^{\circ}C.$

Pin Configuration



Maxim Integrated Products 1

For pricing, delivery, and ordering information, please contact Maxim/Dallas Direct! at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

ABSOLUTE MAXIMUM RATINGS

Supply Voltage0.5V to +4.0V	CML Input Current at IN+, IN25mA
Voltage at IN+, IN(V _{CC} - 1.5V) to (V _{CC} + 0.5V)	CML Output Current at OUT+, OUT25mA
Voltage at CZ+, CZ-, CG+,	Storage Temperature Range55°C to +150°C
CG-, CD+, CD(V _{CC} - 3.5V) to (V _{CC} + 0.5V)	Operating Junction Temperature Range55°C to +150°C
Voltage at SC, SD, EN, TH,	Lead Temperature (soldering, 10s)+300°C
OSM, VREF, and RSSI0.5V to (V_{CC} + 0.5V)	Processing Temperature (Die)+400°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V_{CC} = +3.0V \text{ to } +3.6V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C.$ Typical values are at $V_{CC} = +3.3V$ and $T_A = +25^{\circ}C$, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS			ТҮР	МАХ	UNITS	
		RSSI and SD enabled	At minimum gain		72	86		
Quere la Quere et	laa	(Notes 2, 3)	At maximum gain		94	112	- mA	
Supply Current	Icc	RSSI and SD disabled	At minimum gain		57	69		
		(Notes 2, 3)	At maximum gain		78	94		
Power-Supply Noise Rejection	PSNR	$V_{NOISE} = 100mV_{P-P},$ f _{NOISE} ≤ 10MHz,	$V_{IN} = 1000 \text{mV}_{P-P}$		35		dB	
	1 ONT	$V_{SC} = 2V$ (Note 4)	$V_{IN} = 10mV_{P-P}$		25		ab	
Input Data Rate					2.7		Gbps	
Input Resistance	RIN	Single ended to V _{CC}		40	50	60	Ω	
Input Return Loss		≤2.7GHz			21		dB	
		2.7GHz to 4.0GHz			15		uВ	
Input Common-Mode Level				V _{CC} - 0.3		V _{CC}	V	
Input-Referred Noise		Up to 6GHz at max gain, $C_{CZ} = 0.1 \mu F$			0.26	0.35	mV _{RMS}	
Input Voltage Range	VIN	Differential	6		1200	mV _{P-P}		
Maximum Differential Input		0.0 < linearity < 1.1	$V_{SC} = 0$		700	700		
Voltage for Linear Operation		$0.9 \le \text{linearity} \le 1.1$	$V_{SC} = 2V$		650		mV _{P-P}	
Output Resistance	Rout	Single ended to V _{CC}			50	60	Ω	
Output Deturn Loop		≤2.7GHz		16		dB		
Output Return Loss		2.7GHz to 4.0GHz			11		ив	
			$V_{SC} = 0$		V _{CC} - 0.13			
Output Common-Mode Level		$R_L = 50\Omega$ to V_{CC}	$V_{SC} = 2V$		V _{CC} - 0.28			
		V _{SC} = 0,	$6mV_{P-P} \le V_{IN} \le$ 700mV_{P-P}		±3	±14		
Maximum Differential Output Offset		$R_L = 50\Omega$ to V_{CC} (Note 5)	$700mV_{P-P} \le V_{IN} \le 1200mV_{P-P}$		±8			
		$V_{SC} = 2V,$	$\begin{array}{l} 6mV_{P-P} \leq V_{IN} \leq \\ 700mV_{P-P} \end{array}$		±5.5	±28	mV	
		$R_L = 50\Omega$ to V _{CC} (Note 5)	$700mV_{P-P} \leq V_{IN} \leq 1200mV_{P-P}$		±11			



ELECTRICAL CHARACTERISTICS (continued)

 $(V_{CC} = +3.0V \text{ to } +3.6V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C.$ Typical values are at $V_{CC} = +3.3V$ and $T_A = +25^{\circ}C$, unless otherwise noted.) (Note 1)

PARAMETER	PARAMETER SYMBOL CONDITIONS			MIN	ТҮР	MAX	UNITS
		$R_L = 50\Omega$ to V_{CC}	$V_{SC} = 0$	300	400	500	mV _{P-P}
Differential Output Amplitude	Vout	(Note 6)	$V_{SC} = 2V$	760	920	1050	
Output Amplitude Variation	Δνουτ	$V_{IN} \ge 6mV_{P-P}$, $R_L = 50\Omega$ to V_{CC} (Notes 6, 7)			0.2	1.0	dB
	514		At minimum gain	2.5	2.5 3.4 5.5		
Small Signal Bandwidth	BW	(Note 3)	At maximum gair	2.2	2.9	4.3	GHz
Low-Frequency Cutoff		$C_{CZ} = 0.1 \mu F$			7.6	13	kHz
Deterministic Jitter		(Note 8)			15	50	psp-p
Output Circal Maritar Valtara		$R_{OSM} \ge 2k\Omega$	$V_{OUT} = 920 m V_{P-P}$		2.0		V
Output Signal Monitor Voltage	VOSM	(Note 6)	$V_{OUT} = 400 m V_{P-P}$		0.9		V
Output Signal Monitor Linearity		$0V \le VSC \le 2V$ (Note	6)		±10		%
SC Input Range		(Note 9)		0		2.0	V
AGC Loop Constant		Without external cap V _{SC} = 0 (Note 10)		16		μs	
	DOOL	$R_{RSSI} \ge 2k\Omega$,	$V_{IN} = 2mV_{P-P}$		55		
RSSI Output Voltage	RSSI	V _{SC} = 0 (Note 6)	$V_{IN} = 100 \text{mV}_{P-P}$		1800		mV
		$2mV_{P-P} \le V_{IN} \le 100n$		±2.5	±12	- %	
RSSI Linearity		$6mV_{P-P} \le V_{IN} \le 100n$		±2.5	±8		
Minimum SD Assert Input						2	mV _{P-P}
Maximum SD Assert Input				100			mV _{P-P}
SD Assert Time				10	70		μs
SD Deassert Time		CG+ and CG- are op	pen (Note 11)	10	44		μs
SD Accuracy		(Note 12)			±10		%
		$10mV_{P-P} \le V_{IN} \le 100mV_{P-P}$		2.8	4.5	6.3	dD
SD Hysteresis		$2mV_{P-P} \le V_{IN} \le 10m^{10}$		4.5		dB	
SD Output High Voltage		Sourcing 20µA current		2.4			V
SD Output Low Voltage		Sinking 2mA current				0.44	V
EN Input Low Voltage	VIL					0.8	V
EN Input High Voltage	VIH		2.0			V	
EN Input Low Current	١ _{١L}	V _{IL} = 0				10	μA
EN Input High Current	Ιн	V _{IH} = 2.0V				10	μA
VREF Output Voltage		$R_{VREF} \ge 40 k\Omega$			2.0		V

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Note 1: Electrical characteristics are measured or characterized using a 2²³ - 1PRBS at 2.7Gbps with input edge speeds ≤200ps, unless otherwise noted. Dice are tested at T_A = +25°C only. All AC specifications are guaranteed by design and characterization, unless otherwise noted.

Note 2: Supply current measurement is taken with AC-coupled inputs and excludes output currents into 50Ω loads.

Note 3: Minimum gain is defined as VIN = 1200mVP-P and VOUT = 400mVP-P. Maximum gain is defined as VIN = 6mVP-P and VOUT = 920mV_{P-P}. Reference gain is measured at 100MHz.

Note 4: Power-supply noise rejection is characterized with a 2.7Gbps 1100 pattern on the input. It is calculated by the equation PSNR = $20\log(\Delta V_{CC} / (\Delta V_{OUT}))$, where ΔV_{OUT} is the change in differential output voltage because of power-supply noise. See Power Supply Noise Rejection vs. Frequency in the Typical Operating Characteristics.



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ELECTRICAL CHARACTERISTICS (continued)

(V_{CC} = +3.0V to +3.6V, T_A = -40°C to +85°C. Typical values are at V_{CC} = +3.3V and T_A = +25°C, unless otherwise noted.) (Note 1)

Note 5: See Distribution of Differential Output Offset (Worst-Case Conditions) in the Typical Operating Characteristics.

Note 6: Characterized with a 675Mbps 1-0 pattern.

Note 7: Measurements are taken over an input signal range of 16dB.

Note 8: Deterministic jitter is defined as the arithmetic sum of PWD (pulse-width distortion) and PDJ (pattern-dependent jitter). Deterministic jitter is the difference of total jitter and random jitter, with system jitter calibrated out. It is measured with a 2⁷ - 1PRBS, and 80CIDs with DC-coupled outputs.

Note 9: Typical input resistance of SC pin is $40k\Omega$.

Note 10: AGC loop time constant is measured with a 20dB change in the input and V_{SC} held constant. With an external capacitor C_{CG} of 0.022µF connected between CG+ and CG-, a typical AGC loop time constant of 760µs is achieved.

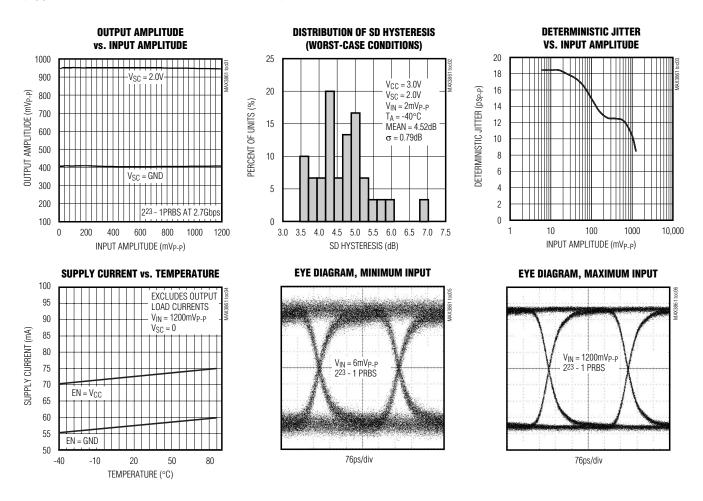
- Note 11: SD deassert time depends on the AGC loop time constant set by C_{CG}.
- Note 12: SD accuracy is defined as the part-to-part variation of the SD threshold at a fixed R_{TH} value.

Note 13: See Distribution of SD Hysteresis (Worst-Case Conditions) in the Typical Operating Characteristics.

Note 14: Measurements are taken over an input signal range of 20dB.

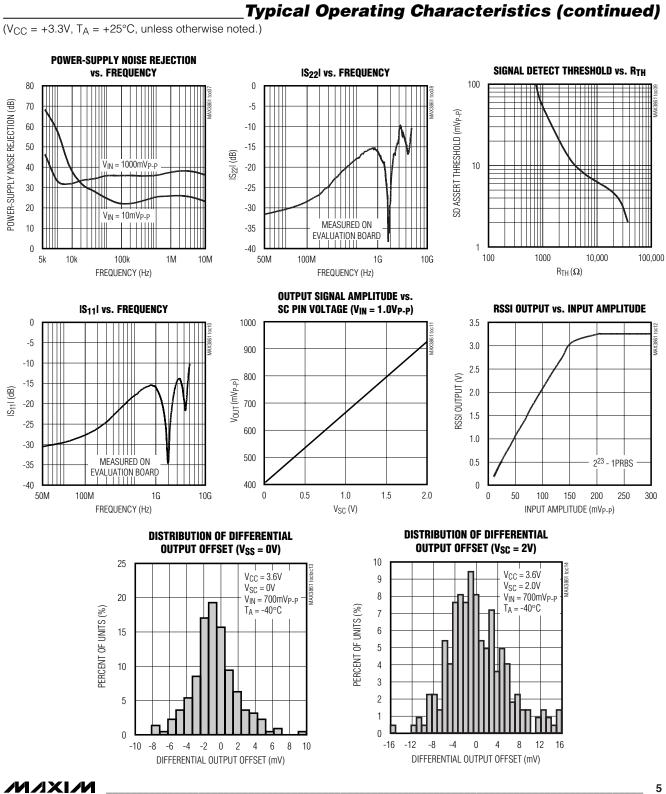
 $(V_{CC} = +3.3V, T_A = +25^{\circ}C, unless otherwise noted.)$

Typical Operating Characteristics



M/IXI/M

MAX3861



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PIN	NAME	FUNCTION
1	ТН	Input Signal Detect Threshold Programming Pin. Attach a resistor between this pin and ground to program the input signal detect assert threshold. Leaving this pin open sets the signal detect threshold to its absolute minimum value (<2mVP-P). See the <i>Design Procedure</i> section.
2, 5, 14, 17	V _{CC}	Supply Voltage Connection. Connect all V _{CC} pins to the board V _{CC} plane.
3	IN+	Positive CML Signal Input with On-Chip Termination Resistor
4	IN-	Negative CML Signal Input with On-Chip Termination Resistor
6	EN	Signal Detect Enable. Set high (\geq 2.0V) or leave open to enable the input signal detection (RSSI and SD) circuitry. Set low (\leq 0.4V) to power-down the input signal detection circuitry.
7	VREF	Reference Voltage Output (2.0V). Connect this pin to the SC pin for maximum output signal swing.
8	SC	Output Amplitude External Control. Ground SC for minimum output amplitude. Apply 2.0V to SC or connect SC directly to VREF for maximum output amplitude.
9, 12, 22	GND	Ground. Connect all GND pins to the board ground plane.
10	CG+	Connection for AGC Loop Capacitor. A capacitor connected between CG+ and CG- sets the AGC loop time constant.
11	CG-	Connection for AGC Loop Capacitor. A capacitor connected between CG+ and CG- sets the AGC loop time constant.
13	OSM	Output Signal Monitor. This DC signal is linearly proportional to the output signal amplitude.
15	OUT-	Negative CML Data Output with On-Chip Back-Termination Resistor
16	OUT+	Positive CML Data Output with On-Chip Back-Termination Resistor
18	SD	Input Signal Detect. Asserts logic low when the input signal level drops below the programmed threshold.
19	RSSI	Received Signal Strength Indicator. Outputs a DC signal that is linearly proportional to the input signal amplitude.
20	CD-	Connection for Signal Detect Capacitor. A capacitor connected between CD+ and CD- sets the offset-cancellation loop time constant of the input signal detection. See the <i>Detailed Description</i> section.
21	CD+	Connection for Signal Detect Capacitor. A capacitor connected between CD+ and CD- sets the offset-cancellation loop time constant of the input signal detection. See the <i>Detailed Description</i> section.
23	CZ-	Connection for Offset-Cancellation Loop Capacitor. A capacitor connected between CZ+ and CZ- sets the offset-cancellation loop time constant of the main signal path. See the <i>Detailed Description</i> section.
24	CZ+	Connection for Offset-Cancellation Loop Capacitor. A capacitor connected between CZ+ and CZ- sets the offset-cancellation loop time constant of the main signal path. See the <i>Detailed Description</i> section.
EP	Exposed Pad	Maxim recommends connecting the exposed pad to board ground.
L		

Pin Description

Detailed Description

Figure 1 is a functional diagram of the MAX3861 automatic gain-control amplifier. The MAX3861 is divided into three sections: main signal path, input signal detection, and output signal detection.

Main Signal Path

The main signal path consists of variable gain amplifiers with CML output levels and an offset cancellation loop. This configuration allows for overall gains ranging from -9.5dB to 43.5dB.

Offset-Cancellation Loop

The offset-cancellation loop partially reduces additional offset at the input. In communications systems using NRZ data with a 50% duty cycle, pulse-width distortion present in the signal or generated by the transimpedance amplifier appears as input offset and is partially removed by the offset cancellation loop. An external capacitor is required between CZ+ and CZ- to compensate the offset cancellation loop and determine the lower 3dB frequency of the signal path.

Input Signal Detection and SD Circuitry

The input signal detection circuitry consists of variable gain amplifiers and threshold voltages. Input signal detection information is compared to an internal reference and creates the RSSI voltage and an internal reference signal. The signal detect (SD) circuitry indicates when the input signal is below the programmed threshold by comparing a voltage proportional to the RSSI signal with internally generated control voltages. The SD threshold is set by a control voltage developed across the external TH resistor (RTH). Two control voltages, VASSERT and VDEASSERT, define the signal detect assert and deassert levels. To prevent SD chatter in the region of the programmed threshold, 2.8dB to 6.3dB of hysteresis is built into the SD assert/deassert function and thus, once asserted, SD is not deasserted until sufficient gain is retained. When input signal detection (SD and RSSI) is not required, tie EN to a TTL low to power-down this circuitry.

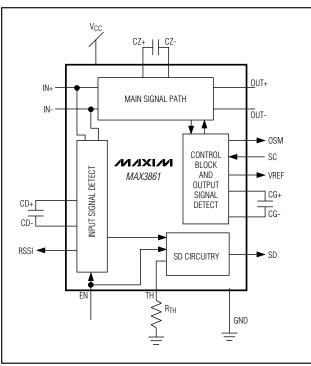


Figure 1. Functional Diagram

Output Signal Monitor and Amplitude Control

Output amplitude typically can be adjusted from 400mVP-P to 920mVP-P by applying a control voltage (0V to 2.0V) to the SC pin. See Output Signal Amplitude vs. SC Pin Voltage in the *Typical Operating Characteristics*. Connect the VREF pin (2.0V) to the SC pin for maximum output amplitude. The output signal monitor pin provides a DC voltage that is linearly proportional to the output signal.

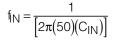
Design Procedure

Program the SD Threshold

The SD threshold is programmed by an external resistor, R_{TH} , between the range of $2mV_{P-P}$ to $100mV_{P-P}$. The circuit is designed to have approximately 4.5dB of hysteresis over the full range. See Signal Detect Threshold vs. R_{TH} graph in the *Typical Operating Characteristics* for proper sizing.

Select the Coupling Capacitors

When AC-coupling is desired, coupling capacitors C_{IN} and C_{OUT} should be selected to minimize the receiver's deterministic jitter. Jitter is decreased as the input low-frequency cutoff (f_{IN}) is decreased.



For ATM/SONET or other applications using scrambled NRZ data, select (C_{IN}, C_{OUT}) \geq 0.1µF, which provides f_{IN} < 32kHz. For Fibre Channel, Gigabit Ethernet, or other applications using 8B/10B data coding, select (C_{IN}, C_{OUT}) \geq 0.01µF, which provides f_{IN} <320kHz.

Setting the Offset-Cancellation Loop Time Constant for Input Signal Detection Circuitry (Selecting C_{CD})

The capacitor between CD+ and CD- determines the time constant of the input signal detection DC offsetcancellation loop. A value of 0.1 μ F for C_{CD} provides a low-frequency cutoff (f_C) below 10kHz. If a lower cutoff frequency is desired, 0.22 μ F gives f_C = 4.5kHz and 0.47 μ F gives f_C = 2.1kHz. To guarantee stable operation, a capacitor of less than 0.01 μ F should not be used.

Setting the Offset-Cancellation Loop Time Constant for the Main Signal Path (Selecting Ccz)

The capacitor between CZ+ and CZ- determines the time constant of the signal path DC offset-cancellation loop. To maintain stability, it is important to keep a one-decade separation between f_{IN} and the low-frequency cutoff (f_{OC}) associated with the DC offset-cancellation circuit. For SONET applications, f_{IN} < 32kHz, so f_{OCMAX} < 3.2kHz. Therefore, C_{CZ} = 0.22µF (f_{OC} = 2.99kHz), C_{CZ} = 0.47µF (f_{OC} = 1.4kHz), or a greater value may be used.To guarantee stable operation, a capacitor of less than 0.01µF should not be used.

Setting the Automatic Gain-Control Loop Time Constant (Selecting CcG)

The automatic gain-control loop time constant is determined by the external capacitor connected between CG+ and CG-. A value of at least 0.0022μ F is recommended

Programming the Output Amplitude (Programming the SC Pin)

Output amplitude can be programmed from 400mVP-P to 920mVP-P by applying a voltage to the SC pin. See Output Signal Amplitude vs SC Pin Voltage in the *Typical Operating Characteristics*.

Applications Information

Wire Bonding Die

For high current density and reliable operation, the MAX3861 uses gold metallization. Make connections to the dice with gold wire only, and use ball-bonding techniques (wedge bonding is not recommended). The MAX3861 has two types of bond pads: the dimensions for square bondpads are 94.4 microns by 94.4 microns; the dimensions for the octagonal bondpads are 33.6 microns per side. Die thickness is 12mils (0.305mm).

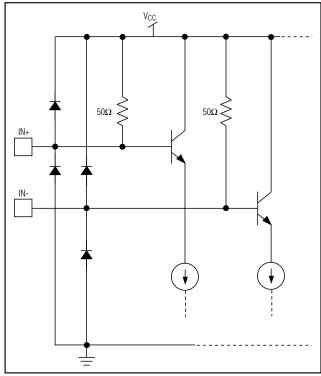


Figure 2. Input Interface

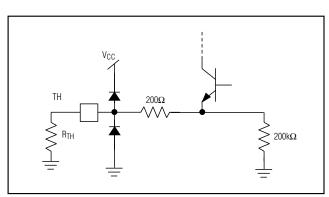


Figure 4. TH Interface

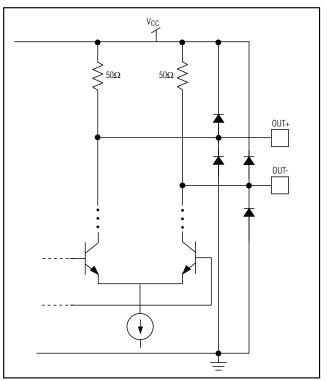


Figure 3. Output Interface

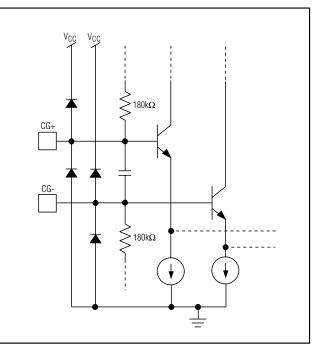


Figure 5. CG Interface

MAX3861

	P	ad Coordinates					
PAD	PAD NAME	COORDINATES (µm)					
1	N.C.	47, 47					
2	EN	44, 264					
3	N.C.	44, 419					
4	V _{CC}	47, 582					
5	IN-	43, 776					
6	IN+	43, 927					
7	V _{CC}	45, 1123					
8	TH	44, 1452					
9	GND	47, 1672					
10	CZ+	306, 1672					
11	CZ-	432, 1672					
12	GND	593, 1671					
13	N.C.	908, 1672					
14	N.C.	1034, 1672					
15	CD+	1181, 1672					
16	CD-	1307, 1672					
17	RSSI	1461, 1672					
18	GND	1662, 1671					
19	SD	1669,1458					
20	V _{CC}	1668, 1126					
21	OUT+	1671, 927					
22	OUT-	1671, 776					
23	V _{CC}	1668, 577					
24	OSM	1669, 272					
25	GND	1661, 47					
26.	N.C.	1356, 47					
27	CG-	1207, 45					
28	CG+	1081, 45					
29	GND	670, 47					
30	SC	513, 45					
31	N.C.	355, 45					
32	VREF	199, 45					

Coordinates are for the center of the pad.

Coordinate 0, 0 is the lower left corner of the passivation open-

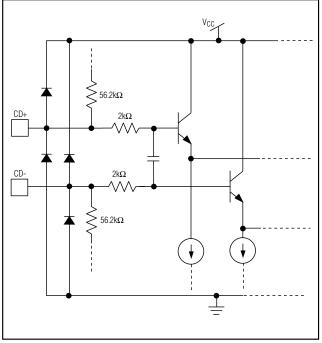


Figure 6. CD Interface

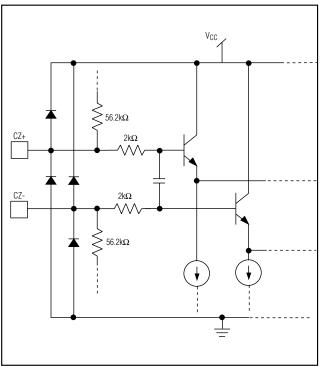


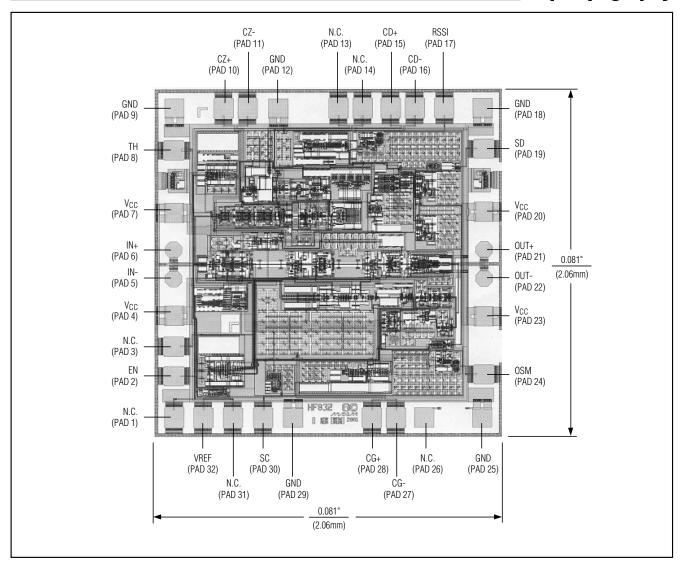
Figure 7. CZ Interface



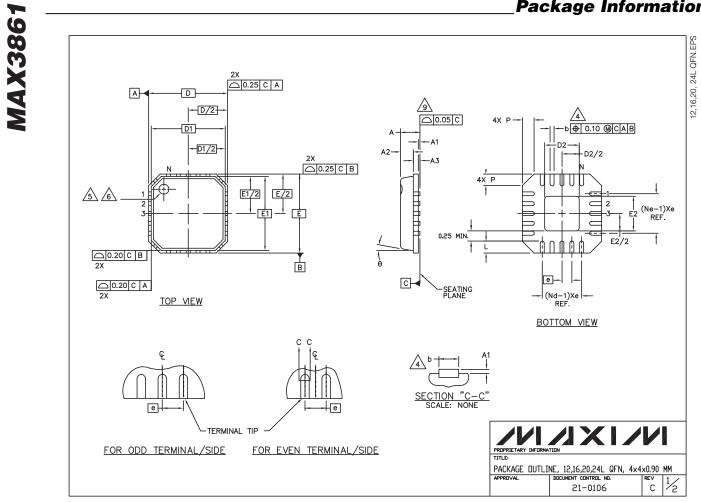
ing for pad 1.

Chip Topography

MAX3861



TRANSISTOR COUNT: 952 Insulated SiGe Bipolar PROCESS: Bipolar F60 DIE SIZE: 2.06mm × 2.06mm



Package Information

Package Information (continued)

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$\begin{array}{c} \hline \begin{array}{ c $	1. DIE THICKNESS ALLOWABL	E IS 0.305mm MAXIM	UM (.012 INCH	IES MAX	імим)							
Nd is THE NUMBER OF TERMINALS IN X-DIRECTION & No is THE NUMBER OF TERMINALS IN X-DIRECTION & M DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.20 AND 0.25mm FROM TERMINAL TIP.Image: the number of terminal tip.Image: the transmission of transmission of the transmission of transmission of the transmission of the transmission of transmission	2. DIMENSIONING & TOLERAN	ICES CONFORM MUST	TO ASME Y14.	5M. – 1	994.							
$\frac{A}{B} \text{ DIMENSION b APPLIES TO PLATED TERMINAL INP.} AND IS MEASURED MARKED. 2020 MARK OR INK/LASER MARKED. A THE PIN #1 IDENTIFIER MUST BE EXISTED ON THE TOP SURFACE OF THE PACKAGE BY USING INDENTATION MARK OR INK/LASER MARKED. A ADDIENT AND SIZE OF THIS FEATURE IS OPTIONAL. A ADDIENT AND SIZE OF THIS FEATURE IS OPTIONAL. A APPLIED FOR EXPOSED PAD AND TERMINALS. EXCLUDE EMBEDDING PART OF EXPOSED PAD FROM MEASURING. MEETS JEDEC MO220. 11. THIS PACKAGE OUTLINE APPLIES TO ANVIL SINGULATION (STEPPED SIDES) AND TO SAW SINGULATION (STRAIGHT SIDES) OFN STYLES. \frac{1}{2} \frac{PITCH VARIATION A}{12} \frac{1}{2} \frac{1}{3} \frac{N}{10} \frac{1}{4} \frac{1}{4} \frac{1}{3} \frac{N}{10} \frac{1}{2} \frac{1}{3} \frac{N}{10} \frac{1}{4} \frac{1}{3} \frac{N}{10} \frac{1}{2} \frac{1}{3} \frac{N}{10} \frac{1}{4} \frac{1}{4} \frac{1}{3} \frac{N}{10} \frac{1}{2} \frac{1}{3} \frac{N}{10} \frac{1}{4} \frac{1}{3} \frac{N}{10} \frac{1}{2} \frac{1}{3} \frac{N}{10} \frac{1}{4} \frac{1}{3} \frac{N}{10} \frac{1}{2} \frac{1}{3} \frac{N}{10} \frac{1}{4} \frac{1}{3} \frac{1}{3} \frac{N}{10} \frac{1}{4} \frac{1}{4} \frac{1}{3} \frac{N}{10} \frac{1}{4} \frac{1}{4} \frac{1}{3} \frac{N}{10} \frac{1}{4} \frac{1}{4} \frac{1}{3} \frac{1}{3} \frac{1}{4} \frac{1}{4} \frac{1}{4} \frac{1}{3} \frac{1}$	Md IS THE NUMBER OF T	ERMINALS IN X-DIREC	TION & TION.					S Y B O		IMENSIO	٧S	NoTE
$\frac{\left \sum_{k=1}^{\infty} \text{THE PIN } \text{M}^{1} \text{ IDENTIFIER MUST BE EXISTED ON THE TOP SUBFACE OF THE PACKAGE BY USING INDENTATION MARK OR INK/LASER MARKED. \frac{\left \sum_{k=1}^{\infty} \text{EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.}\right 7. ALL DIMENSIONS ARE IN MILLIMETERS.8. PACKAGE WARPAGE MAX 0.05mm.A APPLIED FOR EXPOSED PAD AND TERMINALS.EXCLUDE EMBEDDING PART OF EXPOSED PAD FROM MEASURING.10. MEETS JEDEC MO220.11. THIS PACKAGE OUTLINE APPLIES TO ANVIL SINGULATION (STEPPED SIDES)AND TO SAW SINGULATION (STRAIGHT SIDES) QFN STYLES.\frac{\frac{1}{2} \text{ PITCH VARIATION A } \frac{1}{2} \frac{1}{2} \text{ PITCH VARIATION B } \frac{1}{2} \frac{1}{2} \text{ PITCH VARIATION C } \frac{1}{2} \frac{1}{2} \frac{1}{2} \text{ PITCH VARIATION D } \frac{1}{2} \frac{1}{2} \text{ NIN NOM MAX } \frac{1}{2} \frac{1}{2$				D				A1	0.80	0.90	1.00 0.05	
$ \frac{1}{2} EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL. 7. ALL DIMENSIONS ARE IN MILLIMETERS. 8. PACKAGE WARPAGE MAX 0.05mm. APPLIED FOR EXPOSED PAD AND TERMINALS. EXCLUDE EMBEDDING PART OF EXPOSED PAD FROM MEASURING. 10. METS JEDEC MO220. 11. THIS PACKAGE OUTLINE APPLIES TO ANVIL SINGULATION (STEPPED SIDES) AND TO SAW SINGULATION (STERAIGHT SIDES) OFN STYLES. \frac{1}{2} \frac{1}{0.00} \frac{1}{0.0$	THE PIN #1 IDENTIFIER M PACKAGE BY USING INDEN	UST BE EXISTED ON	THE TOP SURFA	ACE OF D.	THE			A3	0.00	0.20 REF		
7. ALL DIMENSIONS ARE IN MILLIMETERS. 8. PACKAGE WARPAGE MAX 0.05mm. A APPLIED FOR EXPOSED PAD AND TERMINALS. EXCLUDE EMBEDDING PART OF EXPOSED PAD FROM MEASURING. 10. MEETS JEDEC MO220. 11. THIS PACKAGE OUTLINE APPLIES TO ANVIL SINGULATION (STEPPED SIDES) AND TO SAW SINGULATION (STRAIGHT SIDES) QFN STYLES. $\frac{V}{V}$ PITCH VARIATION A $\frac{V}{V_{1}} \frac{V}{V_{1}}$ PITCH VARIATION B $\frac{V}{V_{1}} \frac{V}{V_{1}}$ PITCH VARIATION C $\frac{V}{V_{1}} \frac{V}{V_{1}}$ PITCH VARIATION D $\frac{V}{V_{1}} \frac{V}{V_{1}}$ PITCH VARIATION D $\frac{V}{V_{1}} \frac{V}{V_{1}}$ PITCH VARIATION D $\frac{V}{V_{1}} \frac{V}{V_{1}}$ PITCH VARIATION A $\frac{V}{V_{1}} \frac{V}{V_{1}}$ PITCH VARIATION C $\frac{V}{V_{1}} \frac{V}{V_{1}}$ PITCH VARIATION D $\frac{V}{V_{1}} \frac{V}{V_{1}}$ PITCH VARIATION D $\frac{V}{V_{1}} \frac{V}{V_{1}} \frac{V}{V_{1}}$ PITCH VARIATION D $\frac{V}{V_{1}} \frac{V}{V_{1}} $	6 EXACT SHAPE AND SIZE	OF THIS FEATURE IS	OPTIONAL.					D1		3.75 BSC	:	
8. PACKAGE WARPAGE MAX 0.05mm. APPLIED FOR EXPOSED PAD AND TERMINALS. EXCLUDE EMBEDDING PART OF EXPOSED PAD FROM MEASURING. 10. METS JEDEC MO220. 11. THIS PACKAGE OUTLINE APPLIES TO ANVIL SINGULATION (STEPPED SIDES) AND TO SAW SINGULATION (STRAIGHT SIDES) QFN STYLES. $\frac{\frac{1}{2} \frac{1}{2} $	7. ALL DIMENSIONS ARE IN 1	MILLIMETERS.										
$ \frac{1}{2} \text{APPLIED FOR EXPOSED PAD AND TERMINALS.} EXCLUDE EMBEDDING PART OF EXPOSED PAD FROM MEASURING. 10. MEETS JEDEC MO220. 11. THIS PACKAGE OUTLINE APPLIES TO ANVIL SINGULATION (STEPPED SIDES) AND TO SAW SINGULATION (STRAIGHT SIDES) OFN STYLES. \frac{1}{2} \frac{1}{2$	8. PACKAGE WARPAGE MAX	0.05mm.						θ			12	
EXCLUDE EMBEDDING PART OF EXPOSED PAD FROM MEASURING. 10. MEETS JEDEC MO220. 11. THIS PACKAGE OUTLINE APPLIES TO ANVIL SINGULATION (STEPPED SIDES) AND TO SAW SINGULATION (STRAIGHT SIDES) QFN STYLES. $\frac{V}{V} \frac{\text{PITCH VARIATION A V}{V} \frac{V}{V} \frac{\text{PITCH VARIATION B V}{V} \frac{V}{V} \frac{\text{PITCH VARIATION C V}{V} \frac{V}{V} \frac{V}{V} \frac{\text{PITCH VARIATION D V}{V} \frac{V}{V} \frac{V}{V} \frac{V}{V} \frac{\text{PITCH VARIATION D V}{V} \frac{V}{V} \frac$	Λ							·		0.42		
11. THIS PACKAGE OUTLINE APPLIES TO ANVIL SINGULATION (STEPPED SIDES) AND TO SAW SINGULATION (STRAIGHT SIDES) OFN STYLES.			ROM MEASURIN	G.						+		
AND TO SAW SINGULATION (STRAIGHT SIDES) QFN STYLES.	10. MEETS JEDEC MO220.											<u> </u>
Image: Normal Signal	AND TO SAW SINGULATION	N (STRAIGHT SIDES) (QFN STYLES.		·				IS			
Image: Normal Signal	PITCH VARIATION A		RIATION B	Not B				No.				
Nd 3 3 Nd 4 3 Nd 5 3 Nd 6 3 Ne 3 0.75 L 0.50 0.60 0.75 L 0.30 0.40 0.55 b 0.28 0.33 0.40 4 b 0.35 4 b 0.18 0.23 0.30 L 0.	0.80 BSC		OM. I MAX.					-				
Ne 3 3 Ne 4 3 Ne 5 3 Ne 6 3 L 0.50 0.60 0.75 L 0.50 0.60 0.75 L 0.30 0.40 0.55 L b 0.28 0.33 0.40 4 b 0.23 0.35 4 b 0.18 0.23 0.30 L 0.30 0.4 <t< th=""><th></th><th></th><th></th><th></th><th></th><th></th><th></th><th></th><th></th><th></th><th></th><th></th></t<>												
b 0.28 0.33 0.40 4 b 0.23 0.35 4 b 0.18 0.23 0.30 4 b 0.18 0.23 0.30 4 Image: transmission of transmissi transmissi transmission of transmission of transmissio	Ne 3	3 Ne	4	3 Ne		5			Ne		6	3
PROPRIETARY DEGRMATION TITLE PACKAGE DUTLINE, 12,16,20,24L QFN, 4x4x0.90 MM								4				
							TIT PA	IPRIETAR LE ¹ CKAGE	U INFORMAT	E, 12,16,20,2 Document contr	24L QFN, 4	 1x4x0.90 MM

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